

C1

makes the photoresist layer 280 photodefinable. Preferably, the copper foil 235 has a thickness of about 4-20 mils.

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IN THE CLAIMS:

Please cancel claims 18 and 22 without prejudice or disclaimer.

Please amend claims 4 and 11 as follows:

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4. (Amended) A low-pin-count chip package comprising:

C2

a die pad and a plurality of connection pads arranged at the periphery of the die pad wherein the die pad and the connection pads have a concave profile;

a first metal coating on the upper surface of the die pad and the connection pads;

a semiconductor chip disposed on the die pad and electrically coupled to the connection pads;

a package body formed over the semiconductor chip and the connection pads in a manner that a portion of the die pad and a portion of each connection pad extend outward from the bottom of the package body; and

a second metal coating on the lower surface of the die pad and the connection pads,

wherein each of the die pad and the connection pads has a first portion embedded in the package body and a second portion located outside the package body, both the first and second portions have concave profiles.

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11. (Amended) A low-pin-count chip package comprising:

C3

a semiconductor chip;

a plurality of connection pads arranged at the periphery of the semiconductor chip wherein the connection pads have a concave profile;

a first metal coating on the upper surface of the connection pads;

the semiconductor chip having a plurality of bonding pads electrically coupled to the connection pads;

9 J a package body formed over the semiconductor chip and the connection pads in a manner that a portion of each connection pad extends outward from the bottom of the package body; and

a second metal coating on the lower surface of the connection pads,

wherein each of the connection pads has a first portion embedded in the package body and a second portion located outside the package body, both the first and second portions have concave profiles.

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